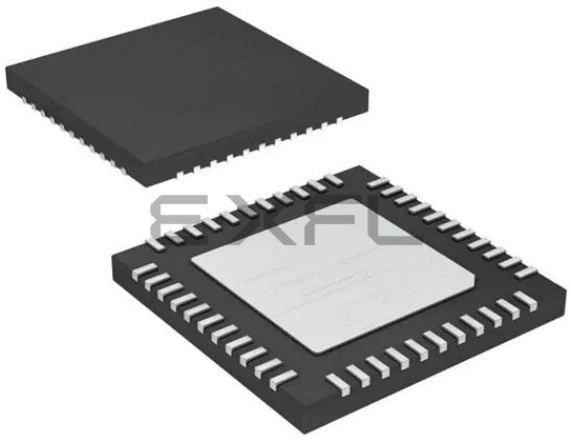
Microchip Technology - DSPIC33FJ16GP304-E/ML Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj16gp304-e-ml

4.8.2 DATA ACCESS FROM PROGRAM MEMORY USING TABLE INSTRUCTIONS

The TBLRDL and TBLWTL instructions offer a direct method of reading or writing the lower word of any address within the program space without going through data space. The TBLRDH and TBLWTH instructions are the only method to read or write the upper 8 bits of a program space word as data.

The PC is incremented by two for each successive 24-bit program word. This allows program memory addresses to directly map to data space addresses. Program memory can thus be regarded as two 16-bit wide word address spaces, residing side by side, each with the same address range. TBLRDL and TBLWTL access the space that contains the least significant data word. TBLRDH and TBLWTH access the space that contains the upper data byte.

Two table instructions are provided to move byte or word sized (16-bit) data to and from program space. Both function as either byte or word operations.

- TBLRDL (Table Read Low): In Word mode, this instruction maps the lower word of the program space location (P<15:0>) to a data address (D<15:0>).

  In Byte mode, either the upper or lower byte of the lower program word is mapped to the lower byte of a data address. The upper byte is selected when Byte Select is '1'; the lower byte is selected when it is '0'.

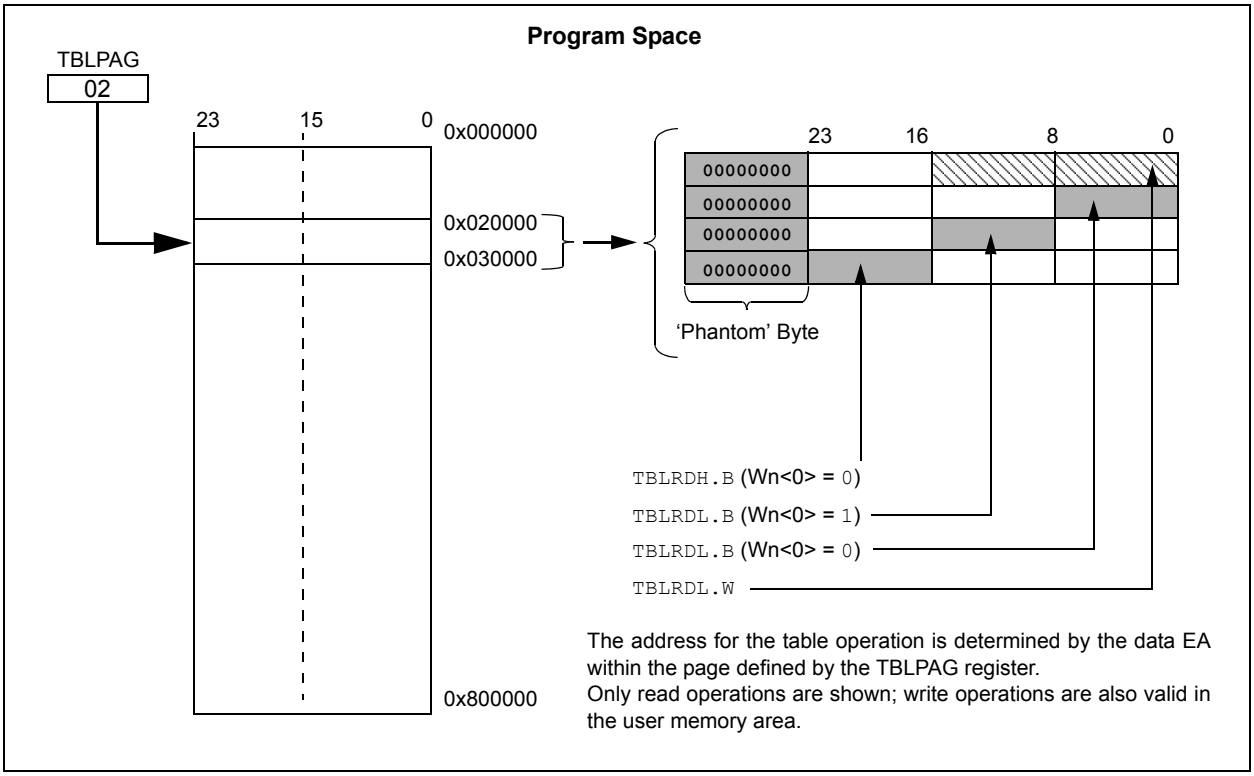
- TBLRDH (Table Read High): In Word mode, this instruction maps the entire upper word of a program address (P<23:16>) to a data address. Note that D<15:8>, the 'phantom byte', will always be '0'.

  In Byte mode, this instruction maps the upper or lower byte of the program word to D<7:0> of the data address, as in the TBLRDL instruction. Note that the data will always be '0' when the upper 'phantom' byte is selected (Byte Select = 1).

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Page register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

FIGURE 4-8: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



NOTES:

REGISTER 5-2: NVMKEY: NONVOLATILE MEMORY KEY REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:	SO = Settable Only bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** Key Register (Write Only) bits

REGISTER 7-11: IPC0: INTERRUPT PRIORITY CONTROL REGISTER 0

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	T1IP<2:0>			—	OC1IP<2:0>		
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	IC1IP<2:0>			—	INT0IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **T1IP<2:0>:** Timer1 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **OC1IP<2:0>:** Output Compare Channel 1 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

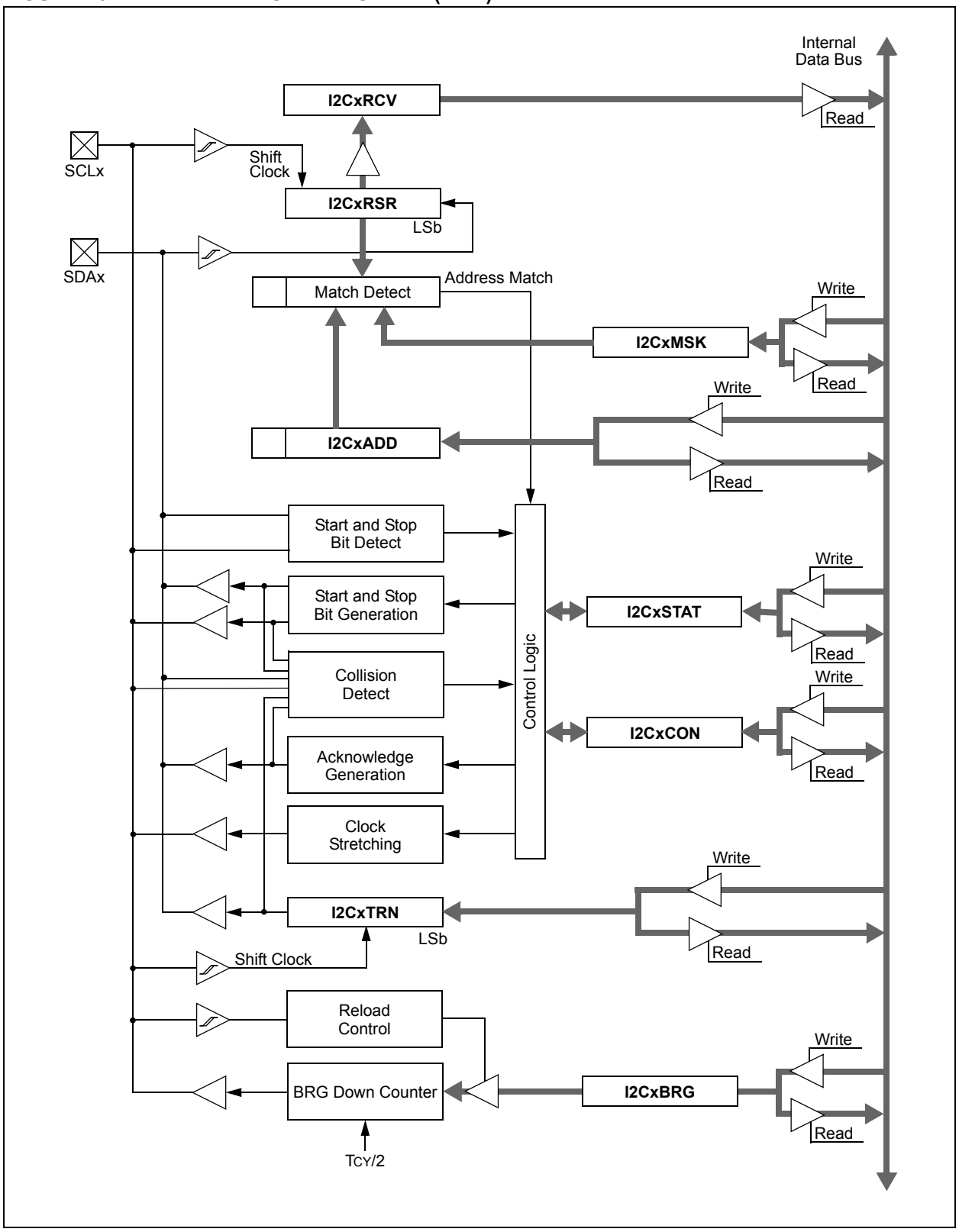
bit 7 **Unimplemented:** Read as '0'

bit 6-4 **IC1IP<2:0>:** Input Capture Channel 1 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **INT0IP<2:0>:** External Interrupt 0 Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

FIGURE 16-1: I²C™ BLOCK DIAGRAM (x = 1)



NOTES:

TABLE 19-2: CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Register	RTSP Effect	Description
FCKSM<1:0>	FOSC	Immediate	Clock Switching Mode bits 1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled 01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled 00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
IOL1WAY	FOSC	Immediate	Peripheral Pin Select Configuration bit 1 = Allow only one reconfiguration 0 = Allow multiple reconfigurations
OSCIOFNC	FOSC	Immediate	OSC2 Pin Function bit (except in XT and HS modes) 1 = OSC2 is clock output 0 = OSC2 is general purpose digital I/O pin
POSCMD<1:0>	FOSC	Immediate	Primary Oscillator Mode Select bits 11 = Primary oscillator disabled 10 = HS Crystal Oscillator mode 01 = XT Crystal Oscillator mode 00 = EC (External Clock) mode
FWDTEN	FWDT	Immediate	Watchdog Timer Enable bit 1 = Watchdog Timer always enabled (LPRC oscillator cannot be disabled. Clearing the SWDTEN bit in the RCON register will have no effect.) 0 = Watchdog Timer enabled/disabled by user software (LPRC can be disabled by clearing the SWDTEN bit in the RCON register)
WINDIS	FWDT	Immediate	Watchdog Timer Window Enable bit 1 = Watchdog Timer in Non-Window mode 0 = Watchdog Timer in Window mode
WDTPRE	FWDT	Immediate	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
WDTPOST<3:0>	FWDT	Immediate	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
ALTI2C	FPOR	Immediate	Alternate I^2C™ pins 1 = I^2C mapped to SDA1/SCL1 pins 0 = I^2C mapped to ASDA1/ASCL1 pins
FPWRT<2:0>	FPOR	Immediate	Power-on Reset Timer Value Select bits 111 = PWRT = 128 ms 110 = PWRT = 64 ms 101 = PWRT = 32 ms 100 = PWRT = 16 ms 011 = PWRT = 8 ms 010 = PWRT = 4 ms 001 = PWRT = 2 ms 000 = PWRT = Disabled
JTAGEN	FICD	Immediate	**JTAG Enable bit** 1 = JTAG enabled 0 = JTAG disabled

19.5 JTAG Interface

dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 devices implement a JTAG interface, which supports boundary scan device testing, as well as in-circuit programming. Detailed information on this interface will be provided in future revisions of the document.

19.6 Code Protection and CodeGuard™ Security

The dsPIC33FJ32GP202/204 and dsPIC33FJ16GP304 product families offer the intermediate implementation of CodeGuard™ Security. CodeGuard Security enables multiple parties to securely share resources (memory, interrupts and peripherals) on a single chip. This feature helps protect individual Intellectual Property in collaborative system designs.

When coupled with software encryption libraries, CodeGuard™ Security can be used to securely update Flash even when multiple IPs reside on the single chip.

The code protection features are controlled by the Configuration registers: FBS and FGS. The Secure segment and RAM is not implemented.

Note:	Refer to **Section 23. *"CodeGuard™ Security"*** (DS70199) in the *"dsPIC33F/PIC24H Family Reference Manual"* for further information on usage, configuration and operation of CodeGuard Security.

TABLE 19-3: CODE FLASH SECURITY SEGMENT SIZES FOR 32 KBYTE DEVICES

CONFIG BITS		
BSS<2:0>=x11 **0K**	VS = 256 IW GS = 11008 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x003FFE 0x004000 0x0057FE
BSS<2:0>=x10 **256**	VS = 256 IW BS = 768 IW GS = 10240 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x003FFE 0x004000 0x0057FE
BSS<2:0>=x01 **768**	VS = 256 IW BS = 3840 IW GS = 7168 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x003FFE 0x004000 0x0057FE
BSS<2:0>=x00 **1792**	VS = 256 IW BS = 7936 IW GS = 3072 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x003FFE 0x004000 0x0057FE

TABLE 19-4: CODE FLASH SECURITY SEGMENT SIZES FOR 16 KBYTE DEVICES

CONFIG BITS		
BSS<2:0>=x11 **0K**	VS = 256 IW GS = 5376 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x002BFE
BSS<2:0>=x10 **256**	VS = 256 IW BS = 768 IW GS = 4608 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x002BFE
BSS<2:0>=x01 **768**	VS = 256 IW BS = 3840 IW GS = 1536 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x002BFE
BSS<2:0>=x00 **1792**	VS = 256 IW BS = 5376 IW	0x000000 0x0001FE 0x000200 0x0007FE 0x000800 0x001FFE 0x002000 0x002BFE

TABLE 20-1: SYMBOLS USED IN OPCODE DESCRIPTIONS (CONTINUED)

Field	Description
Wm*Wm	Multiplicand and Multiplier working register pair for Square instructions ∈ {W4 * W4,W5 * W5,W6 * W6,W7 * W7}
Wm*Wn	Multiplicand and Multiplier working register pair for DSP instructions ∈ {W4 * W5,W4 * W6,W4 * W7,W5 * W6,W5 * W7,W6 * W7}
Wn	One of 16 working registers ∈ {W0..W15}
Wnd	One of 16 destination working registers ∈ {W0...W15}
Wns	One of 16 source working registers ∈ {W0...W15}
WREG	W0 (working register used in file register instructions)
Ws	Source W register ∈ { Ws, [Ws], [Ws++], [Ws--], [++Ws], [--Ws] }
Wso	Source W register ∈ { Wns, [Wns], [Wns++], [Wns--], [++Wns], [--Wns], [Wns+Wb] }
Wx	X data space prefetch address register for DSP instructions ∈ {[W8]+ = 6, [W8]+ = 4, [W8]+ = 2, [W8], [W8]- = 6, [W8]- = 4, [W8]- = 2, [W9]+ = 6, [W9]+ = 4, [W9]+ = 2, [W9], [W9]- = 6, [W9]- = 4, [W9]- = 2, [W9 + W12], none}
Wxd	X data space prefetch destination register for DSP instructions ∈ {W4...W7}
Wy	Y data space prefetch address register for DSP instructions ∈ {[W10]+ = 6, [W10]+ = 4, [W10]+ = 2, [W10], [W10]- = 6, [W10]- = 4, [W10]- = 2, [W11]+ = 6, [W11]+ = 4, [W11]+ = 2, [W11], [W11]- = 6, [W11]- = 4, [W11]- = 2, [W11 + W12], none}
Wyd	Y data space prefetch destination register for DSP instructions ∈ {W4...W7}

TABLE 22-8: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

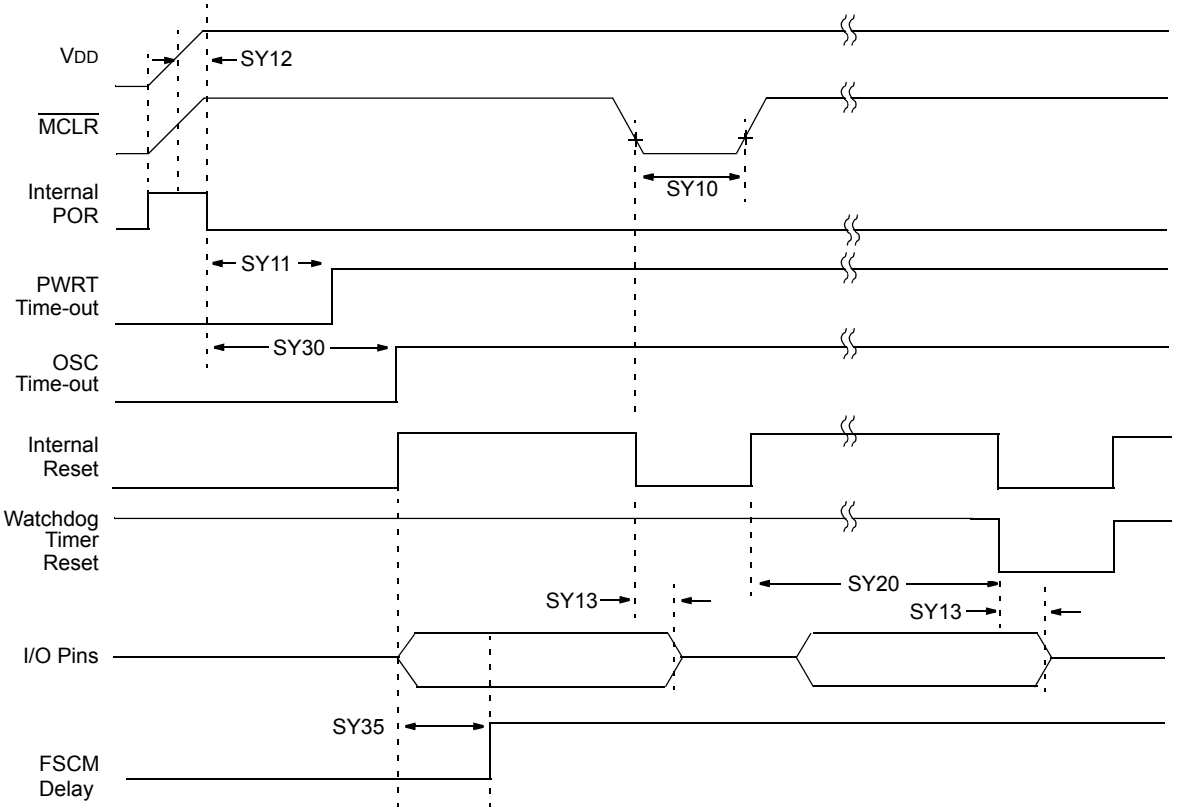
DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+125°C for Extended				
Parameter No.	**Typical(2)**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
Doze Current (IDOZE)(1)							
DC73a	41	51	1:2	mA	-40°C	3.3V	40 MIPS
DC73f	20	28	1:64	mA			
DC73g	19	24	1:128	mA			
DC70a	40	46	1:2	mA	+25°C	3.3V	40 MIPS
DC70f	18	20	1:64	mA			
DC70g	18	20	1:128	mA			
DC71a	40	46	1:2	mA	+85°C	3.3V	40 MIPS
DC71f	18	25	1:64	mA			
DC71g	18	20	1:128	mA			
DC72a	39	55	1:2	mA	+125°C	3.3V	40 MIPS
DC72f	18	30	1:64	mA			
DC72g	18	25	1:128	mA			

Note 1: IDOZE is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDOZE measurements are as follows:

- Oscillator is configured in EC mode and external clock active, OSC1 is driven with external square wave from rail-to-rail with overshoot/undershoot < 250 mV
- CLKO is configured as an I/O input pin in the Configuration Word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{\text{MCLR}}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero and unimplemented PMDx bits are set to one)
- CPU executing `while(1)` statement
- JTAG is disabled

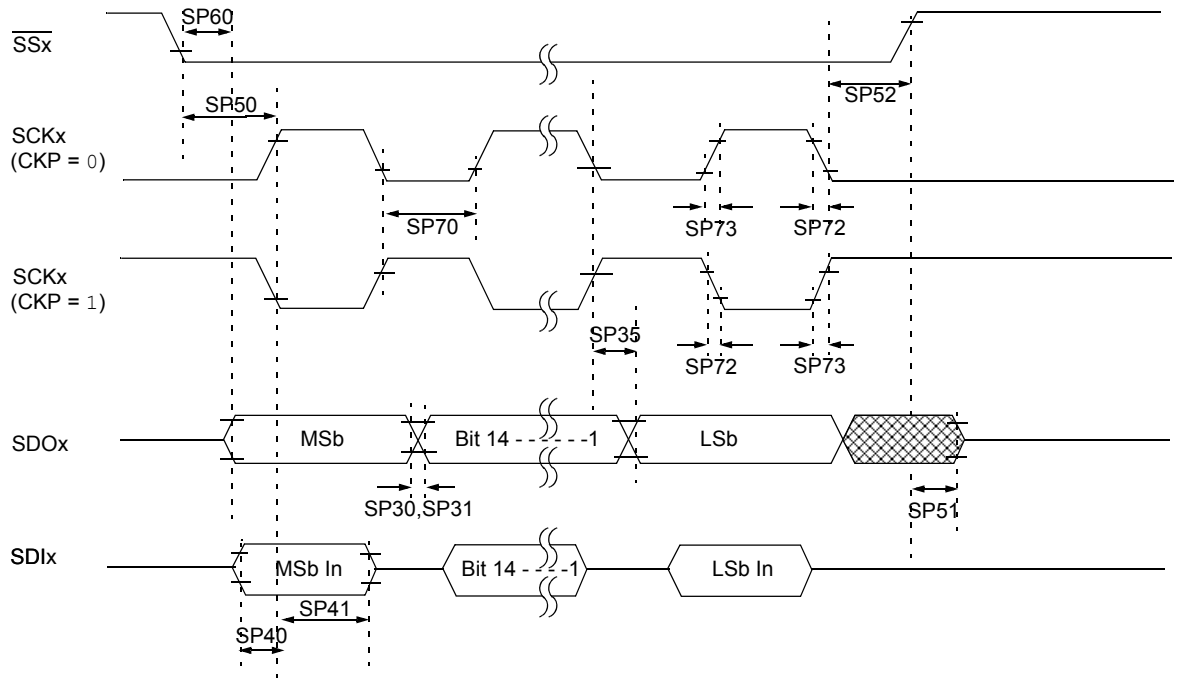
2: Data in the “Typ” column is at 3.3V, +25ºC unless otherwise stated.

FIGURE 22-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING CHARACTERISTICS



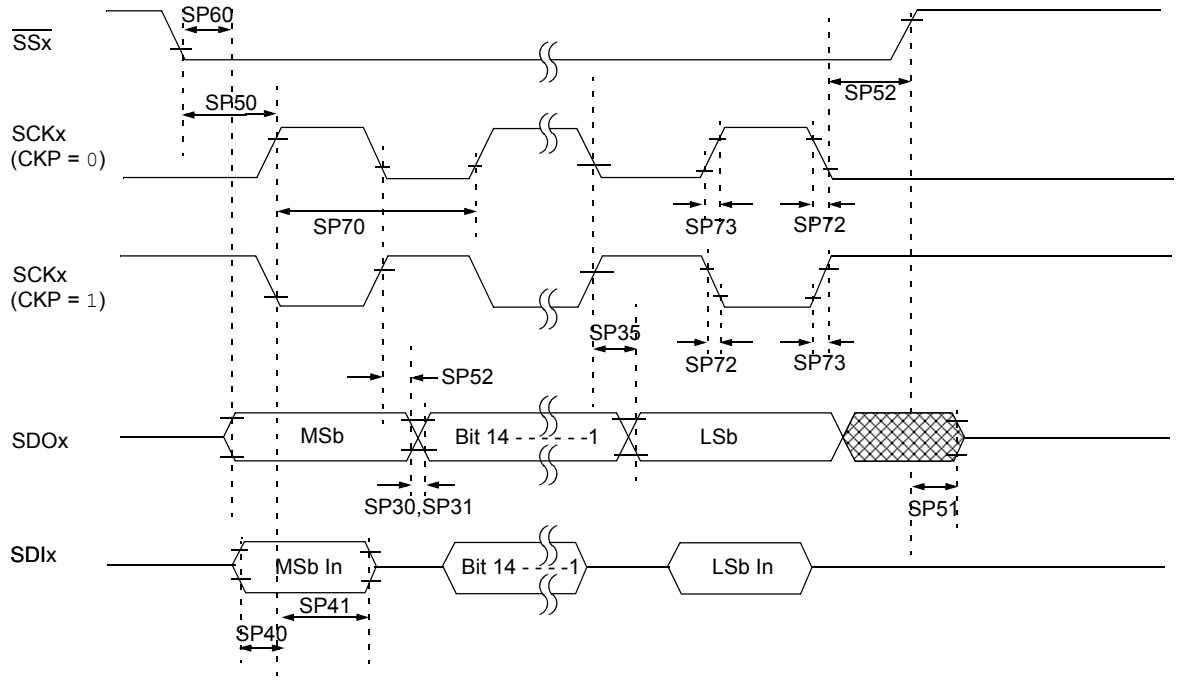
Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-13: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



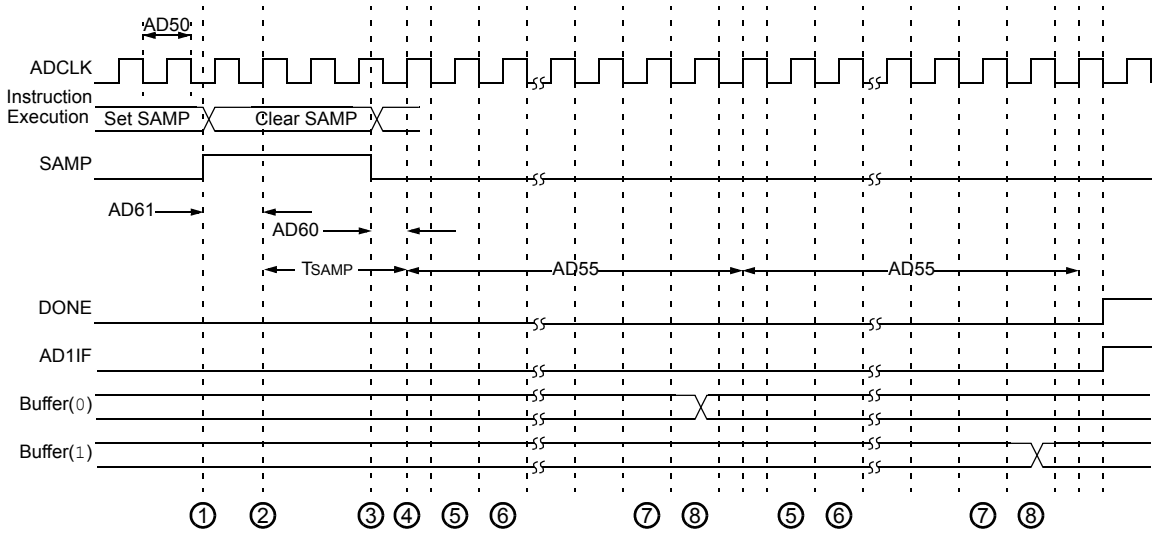
Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-14: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 1, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-22: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



① – Software sets AD1CON. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

③ – Software clears AD1CON. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

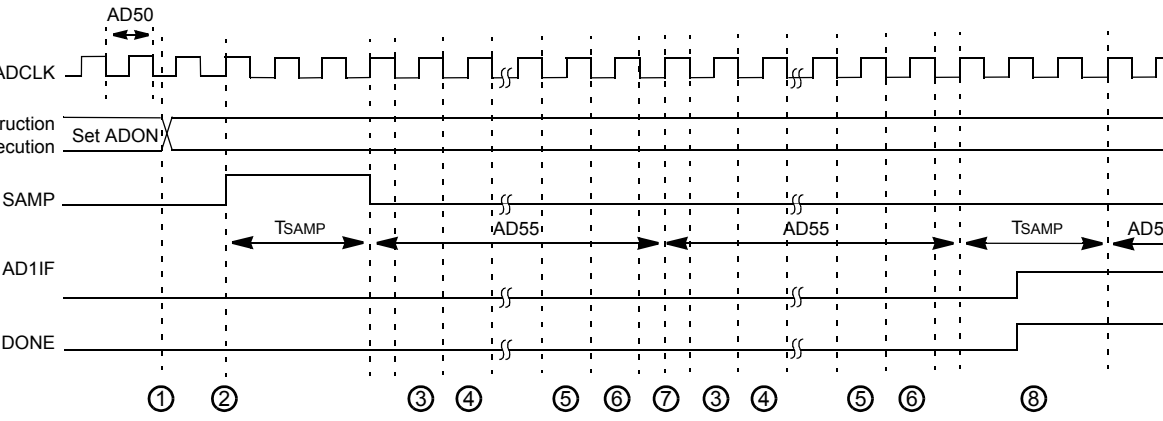
⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

FIGURE 22-23: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



① – Software sets AD1CON. ADON to start AD operation.

② – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

③ – Convert bit 9.

④ – Convert bit 8.

⑤ – Convert bit 0.

⑥ – One TAD for end of conversion.

⑦ – Begin conversion of next channel.

⑧ – Sample for time specified by SAMC<4:0>.

TABLE 23-7: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for High Temperature				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤1.8 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA0, RA1, RB5, RB6, RB8, RB9, RB14	—	—	0.4	V	IOL ≤3.6 mA, VDD = 3.3V See **Note 1**
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSCO, CLKO, RA3	—	—	0.4	V	IOL ≤6 mA, VDD = 3.3V See **Note 1**
DO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -1.8 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA0, RA1, RB5, RB6, RB8, RB9, RB14	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSCO, CLKO, RA3	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V See **Note 1**
DO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -1.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -1.85 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -1.4 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA0, RA1, RB5, RB6, RB8, RB9, RB14	1.5	—	—	V	IOH ≥ -3.9 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -3.7 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins -OSCO, CLKO, RA3	1.5	—	—	V	IOH ≥ -7.5 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -6.8 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

TABLE 23-15: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Reference Inputs							
HAD08	IREF	Current Drain	— —	250 —	600 50	µA µA	ADC operating, See **Note 1** ADC off, See **Note 1**

Note 1: These parameters are not characterized or tested in manufacturing.

2: These parameters are characterized, but are not tested in manufacturing.

TABLE 23-16: ADC MODULE SPECIFICATIONS (12-BIT MODE)(3)

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
ADC Accuracy (12-bit Mode) – Measurements with External VREF+/VREF-(1)							
HAD20a	Nr	Resolution(3)	12 data bits			bits	—
HAD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD23a	GERR	Gain Error	-2	—	10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
HAD24a	EOFF	Offset Error	-3	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V
ADC Accuracy (12-bit Mode) – Measurements with Internal VREF+/VREF-(1)							
HAD20a	Nr	Resolution(3)	12 data bits			bits	—
HAD21a	INL	Integral Nonlinearity	-2	—	+2	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD22a	DNL	Differential Nonlinearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD23a	GERR	Gain Error	2	—	20	LSb	VINL = AVSS = 0V, AVDD = 3.6V
HAD24a	EOFF	Offset Error	2	—	10	LSb	VINL = AVSS = 0V, AVDD = 3.6V
Dynamic Performance (12-bit Mode)(2)							
HAD33a	FNYQ	Input Signal Bandwidth	—	—	200	kHz	—

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

FIGURE 24-5: VOL – 2x DRIVER PINS

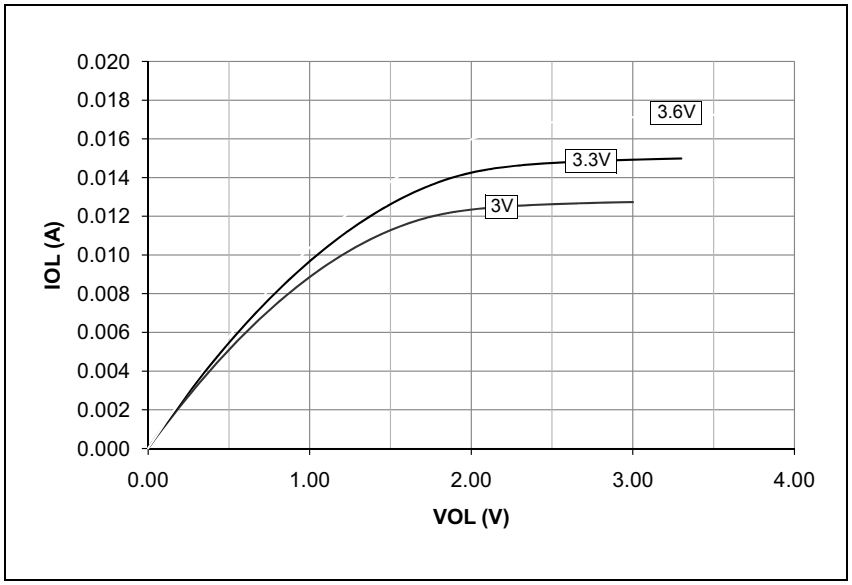


FIGURE 24-6: VOL – 4x DRIVER PINS

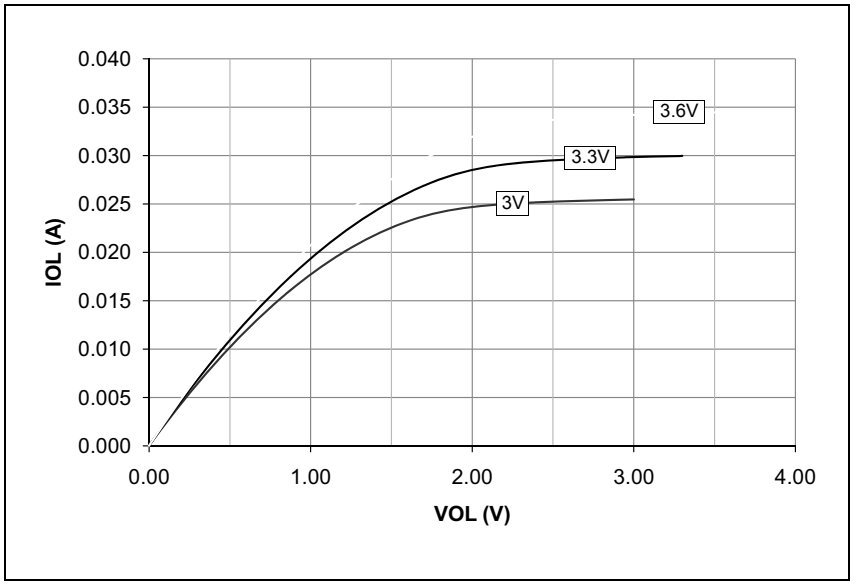


FIGURE 24-7: VOL – 8x DRIVER PINS

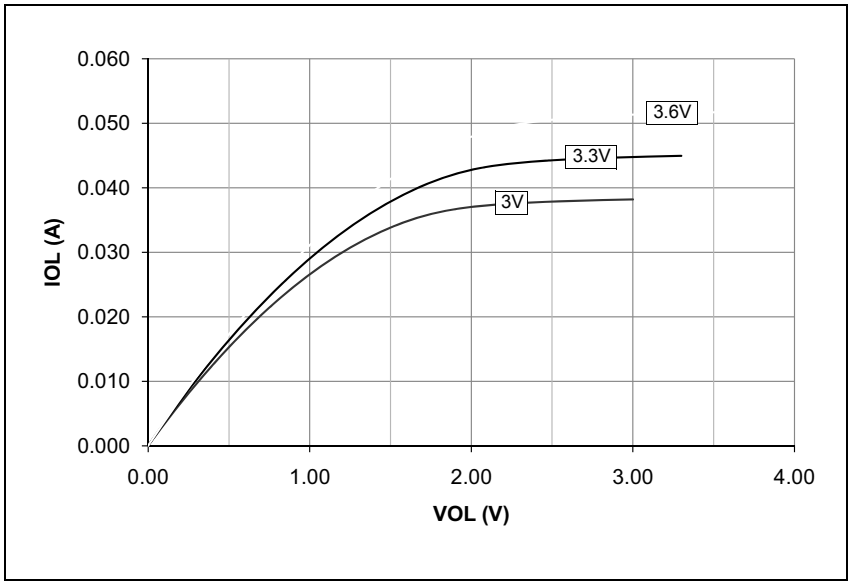
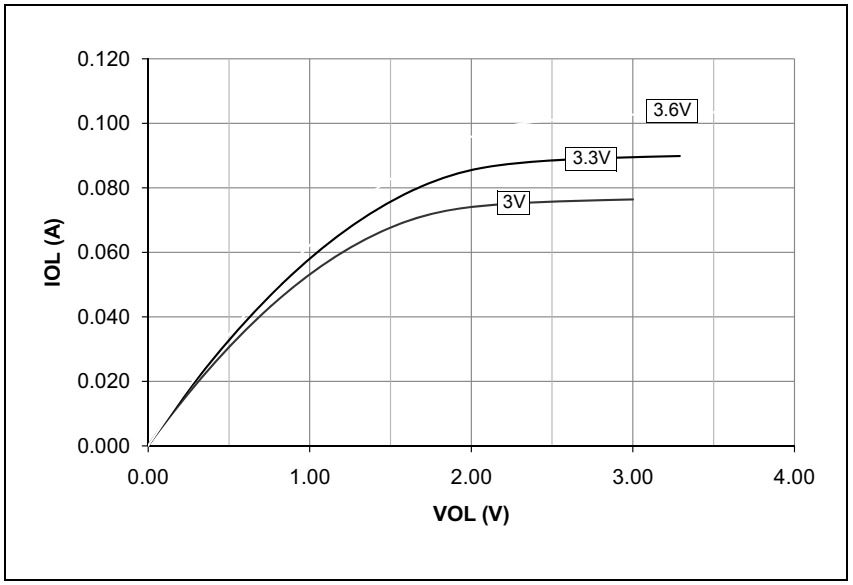


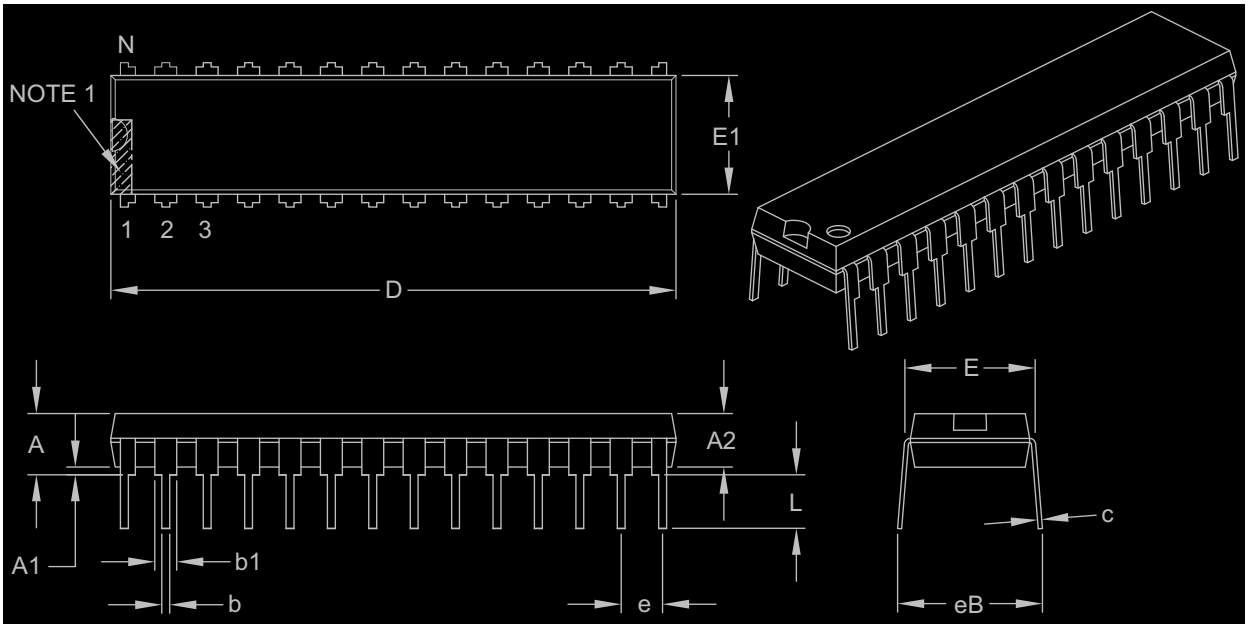
FIGURE 24-8: VOL – 16x DRIVER PINS



25.2 Package Details

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.200
Molded Package Thickness	A2	.120	.135	.150
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.335
Molded Package Width	E1	.240	.285	.295
Overall Length	D	1.345	1.365	1.400
Tip to Seating Plane	L	.110	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.040	.050	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

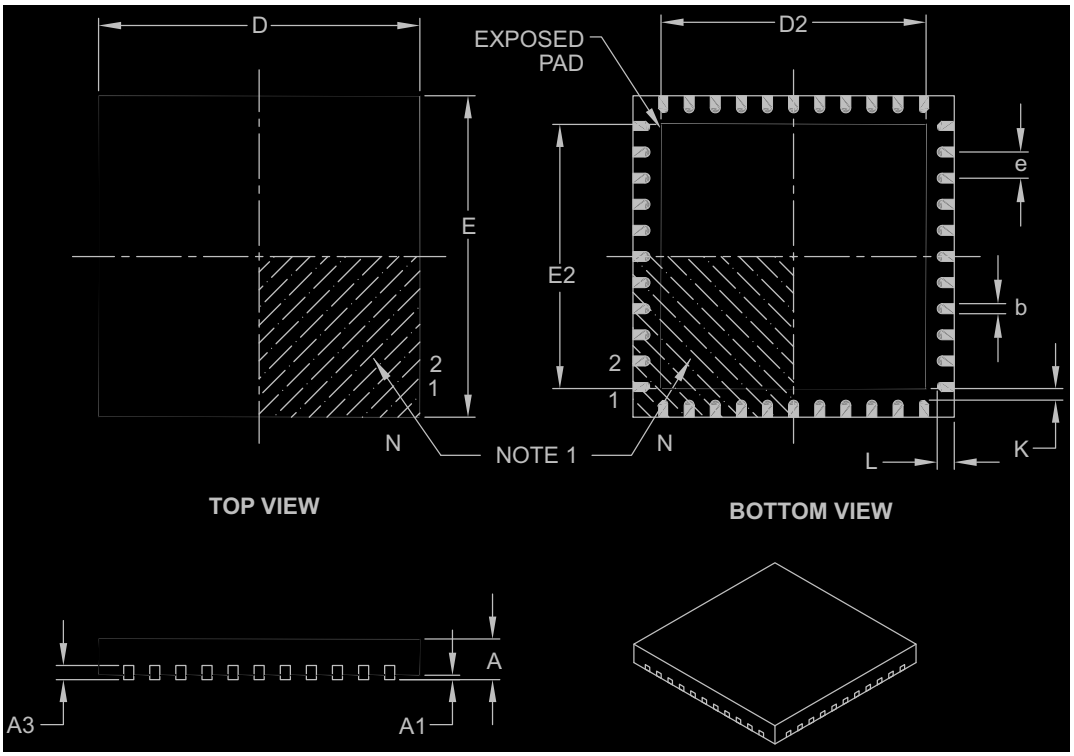
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.30	6.45	6.80
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.30	6.45	6.80
Contact Width	b	0.25	0.30	0.38
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	–	–

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

Note the following details of the code protection feature on Microchip devices:

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- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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